



BOARD LEVEL COOLING – 3719

3719 is a series of square pin fin board level heat sinks designed to cool BGA and FPGA devices. Representative image only.

ORDERING INFORMATION

Part Number	Device Type
371924B00000G	BGA, FPGA
371924B00032G	BGA, FPGA
371924B00034G	BGA, FPGA



HEAT SINK DETAILS

Property	Details
Material	Aluminum
Finish	Black Anodize
Device Attachment Options	Epoxy, Tape
Thermal Interface Material: 371924B00000G	-
Thermal Interface Material: 371924B00000G	T405R Chomerics Tape for Metal Surfaces
Thermal Interface Material: 371924B00000G	T410R Chomerics Tape for Plastic Surfaces

Property	Details
Heat Sink Width (mm)	35.0
Heat Sink Length (mm)	35.0
Heat Sink Height (mm)	14.0
Heat Sink Mounting Direction	Horizontal, Vertical

MECHANICAL & PERFORMANCE

Drawing dimensions are shown as: in., (mm)

